



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20240703000.0
Datasheet for UCC21550x-Q1, UCC21330x, UCC21550x, UCC21330x-Q1
Information Only

Date: July 03, 2024
To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the Change Management team.

Sincerely,

Change Management Team
SC Business Services

20240703000.0
Information Only Datasheet
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
UCC21330BDR	NULL
UCC21330BQDRQ1	NULL
UCC21550ADWR	NULL
UCC21550AQDWRQ1	NULL
UCC21550BDWR	NULL
UCC21550BQDWRQ1	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20240703000.0	PCN Date:	July 03, 2024
Title:	Datasheet for UCC21550x-Q1, UCC21330x, UCC21550x, UCC21330x-Q1		
Customer Contact:	Change Management team	Dept:	Quality Services
Change Type:	Electrical Specification		

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.



UCC21550-Q1
SLUSEU6C – MAY 2023 – REVISED JUNE 2024

Changes from Revision B (November 2023) to Revision C (June 2024)	Page
• Removed HBD ESD and CDM ESD classification levels per datasheet standard change.....	1
• Added new device spins.....	1
• Changed typical application schematic disable capacitor naming.....	1
• Added DWK package drawing.....	3
• Added recommendation on DT capacitor size.....	3
• Added ch-ch isolation voltage for DWK package.....	5
• Changed HBM ESD from +/-4000V to +/-2000V.....	5
• Added 12V UVLO spin.....	5
• Added thermal information for DWK package.....	5
• Updated overvoltage category of ≤600Vrms from I-IV to I-III per latest standard.....	7
• Updated overvoltage category of ≤1000Vrms from I-III to I-II per latest standard.....	7
• Updated VDE to latest standard.....	7
• Added safety limiting values for DWK package.....	8
• Changed test condition from EN=VCC to DIS=GND.....	9
• Changed VCC quiescent current typical and max to tighten spec.....	9
• Changed VDD quiescent current typical and max.....	9
• Added 12V UVLO spin.....	9
• Added minimum propagation delay of 26ns.....	10
• Changed typical DIS delay from 49ns to 48ns.....	10
• Changed typical minimum input pulse from 9ns to 12ns.....	10
• Changed TDDb curve to match basic isolation.....	11
• Added thermal derating limiting current and limiting power curves for DWK package.....	11
• Added typical characteristics plot for 12V UVLO.....	13
• Changed plot titles to reflect DIS spins.....	13
• Changed typical application schematic disable capacitor naming.....	27

Changes from Revision * (January 2024) to Revision A (June 2024)	Page
• Changed isolation rating to 3kVrms.....	1
• Added new device spins.....	1
• Changed typical application schematic disable capacitor naming.....	1
• Added recommendation on DT capacitor size.....	3
• Added recommend operating voltage for 5V and 12V UVLO spins.....	4
• Changed CTI from >600V to >400V.....	6
• Changed material group from I to II.....	6
• Changed test condition from EN=VCC to DIS=GND.....	8
• Added UVLO values for 5V and 12V UVLO spins.....	8
• Changed typical DIS response delay from 49ns to 48ns.....	9
• Separated tDM spec from -40°C to 150°C tDM=5ns max into two temperature ranges.....	9
• Changed maximum PWD to 5ns.....	9
• Changed safety limiting curves to reflect device characteristics.....	10
• Changed TDDDB curve to match basic isolation.....	10
• Added typical characteristics plot for 5V and 12V UVLO.....	11
• Changed plot titles to reflect DIS spins.....	11
• Changed typical application schematic disable capacitor naming.....	25

Changes from Revision A (November 2023) to Revision B (June 2024)	Page
• Added new device spins.....	1
• Changed typical application schematic disable capacitor naming.....	1
• Added DWK package drawing.....	3
• Added DIS pin description.....	3
• Added recommendation on DT capacitor size.....	3
• Added ch-ch isolation voltage for DWK package.....	5
• Changed HBM ESD from +/-4000V to +/-2000V.....	5
• Added 12V UVLO spin.....	5
• Added thermal information for DWK package.....	5
• Updated overvoltage category of ≤600Vrms from I-IV to I-III per latest standards.....	7
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The datasheet number will be changing.

Device Family	Change From:	Change To:
UCC21550x-Q1	SLUSEU6B	SLUSEU6C
UCC21330x	SLUSFE4	SLUSFE4A
UCC21550x	SLUSE89A	SLUSE89B
UCC21330x-Q1	SLUSFF3	SLUSFF3A

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/UCC21550-Q1>

<http://www.ti.com/product/UCC21330>

<http://www.ti.com/product/UCC21550>

<http://www.ti.com/product/UCC21330-Q1>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only.

Changes to product identification resulting from this PCN:

None.

Product Affected:

UCC21550AQDWRQ1	UCC21550BQDWRQ1	UCC21330BDR	UCC21550ADWR
UCC21550BDWR	UCC21330BQDRQ1		

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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